

FOR IMMEDIATE RELEASE

TRI to Showcase Semiconductor Inspection Solutions at SEMICON West 2026

[September 14, 2026 – San Jose, CA] Test Research, Inc. (TRI), the leading test and inspection systems provider for the electronics manufacturing industry, will be exhibiting at SEMICON West held at Moscone Center, San Francisco, CA, USA from October 13 - 15, 2026.

Visit TRI's Booth No. 5972 to learn more about the latest Advanced WLP/PLP and SEMI Back-End Package Inspection and metrology solutions. TRI's Inspection and Metrology Applications include: Chiplet & Chip-on-Wafer (CoW), System-in-Package (SiP), Advanced WLP, TSV Metrology, μ Bump, Cu Pillar, Surface Topology, Profiling, Wafer Thickness, Thin Film Thickness, Patterned Wafer, Inner Crack / Chipping, After Sawing Defects, Die Underfill, Glue, Epoxy & Flux, Wafer Bumping and Die / Wire Bonding.



TRI will exhibit its back-end inspection solutions, including the 3D SEMI AOI [TR7900Q SII](#) and [TR7700Q SII-S](#) with AI-Powered 3D Inspection that can inspect die, wire diameters of up to 15 μ m (0.6 mil), SiP, underfill, bumps, and more. The TR7900Q SII fully integrates with the loader/unloader module to ease the handling of strips and magazines.

TRI will also exhibit the back-end inspection solutions, the [TR7007Q SII-S](#) for C4 bumps ($\sim 100 \mu$ m $\varnothing$), Mini-LED, and 008004 paste inspection applications. The lineup will also include an X-ray Inspection Demo Station. TRI's SEMI AXI solutions can inspect C4 bumps, Cu pillars, TGV, and more.

Visit TRI at Booth No. 5972 at SEMICON West 2026 to explore the future of SEMI inspection.

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About Test Research, Inc. (TRI)

TRI offers the most robust product portfolio in the industry for Automated Test and Inspection solutions. TRI provides the most cost-effective solutions to meet a comprehensive range of manufacturing Test and Inspection requirements. Learn more at <http://www.tri.com.tw>. For sales and service information, please write to us at marketing@tri.com.tw or call +886-2-2832 8918.